

U.S. Department of Commerce, Patent and Trademark Office				Attorney Docket No.: 026-0047	
				Application No.: 10/813,886	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Applicant(s): Ligang Zhang et al.	
(Use several sheets if necessary)				Filing Date: March 31, 2004	
				Group Art Unit: Not yet assigned	
				Date Submitted: April 30, 2004	
U.S. Patent Documents					
*Examiner Initial		Document Number	Date	Name	
JEM	AA	5,083,236	Jan. 21, 1992	Chason et al.	
JEM	AB	5,461,353	Oct. 24, 1995	Eberhardt	
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	AH				
	AI				
	AJ				
	AK				
Foreign Patent Documents					
		Document	Date	Country	Translation
					Yes No
JEM	AL	0 675 539 A2	Oct. 4, 1995	Europe	
JEM	AM	WO 02/067326 A2	Aug. 29, 2002	PCT	
	AN				
	AP				
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)					
	AR	"Unitive - CSP On the Edge", Unitive Inc. 2003 (from website - http://www.unitive.com/cspedge/index.cfm), 2 pages.			
	AS	"Unitive Design Guidelines", www.unitive.com , 2001, pp. 1-18.			
	AT				
Examiner	J. E. Matlack		Date Considered 3-16-06		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.					

PTO/SB/08A (Substitute for form 1449/PTO)	Attorney Docket No.: 026-0047
	Application No.: 10/813,886
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	First Named Inventor: Ligang Zhang
	Filing Date: March 31, 2004
	Group Art Unit: 2811
	Examiner Name: Quang D. Vu
Sheet 1 of 1	Date Submitted: July 13, 2005

[illegible]

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¹Applicant's unique citation designation number (optional).

²See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04.

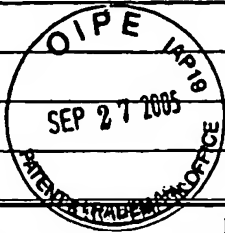
¹Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3)

⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document.

⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible.

*Applicant is to place a check mark here if English language Translation is attached.

PTO/SB/08B (Substitute for form 1449/PTO)		Attorney Docket No.: 026-0047	
		Application No.: 10/813,886	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		First Named Inventor: Ligang Zhang	
		Filing Date: March 31, 2004	
		Group Art Unit: 2811	
		Examiner Name: Jennifer E. Matisiak	
Sheet 1 of 1		Date Submitted: September 23, 2005	



NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of author (In CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
JEM	AA	FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100.	
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Examiner Signature		Jennifer E. Matisiak	Date Considered
			3-16-06

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